



In-line Metrology for 3D Structure of Semiconductor Devices
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Semiconductor's development path has 2 ways, which are shrinking and 3D structural. Recently shrinking way has been shrunk due to technical difficulties and development cost. 3D devices can be extended with technical limitations. However, 3D devices have many difficulties for monitoring because 3D structures need to measure many things for better precision and accuracy. For Metrology and Inspection there are a lot of challenges. For example, one of main critical issue is to find embedded defects at middle of via contact. And even though defect can be detected by some inspection tools we don't know where defect is. In this presentation we can review 3D devices' monitoring issues and their solutions.

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